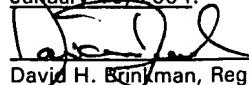




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 David H. Brinkman, Reg. No. 40,532

1/15/04
Date

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Eric Austin et al.
Serial No.: 09/898,601
Filed: July 3, 2001
Confirmation No.: 3051
Group Art Unit: 1722
Examiner: Davis, Robert B.
Title: **APPARATUS FOR VACUUM ENCAPSULATION OF SEMICONDUCTOR CHIP PACKAGES (As Amended)**
Atty Docket: NOR-865B

Cincinnati, Ohio 45202

January 15, 2004

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Office Action mailed on September 23, 2003,
please amend the above-identified application as follows:

Amendments to the Title begin on page 2 of this paper.

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.

Amendments to the Drawings begin 9 on page of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Amendments to the Abstract begin 10 on page of this paper.

Remarks/Arguments begin on page 11 of this paper.

An **Appendix** including amended drawing figures is attached following page 15 of this paper.

Amendments to th Title:

APPARATUS AND METHOD FOR VACUUM ENCAPSULATION OF
SEMICONDUCTOR CHIP PACKAGES